



SLOVENSKI STANDARD
SIST EN IEC 63251:2024

01-februar-2024

Metoda preskušanja mehanskih lastnosti toplotno obremenjenih zvijavih optoelektričnih tiskanih vezij

Test Method for Mechanical Property of Flexible Opto-Electric Circuit Boards under Thermal Stress

Prüfverfahren für mechanische Eigenschaften von elektrisch-optischen Leiterplatten unter Wärmebeanspruchung

Méthode d'essai des propriétés mécaniques des circuits opto-électriques souples sous contrainte thermique

Ta slovenski standard je istoveten z: EN IEC 63251:2023

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ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards plošče

SIST EN IEC 63251:2024

en

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 63251

December 2023

ICS 31.180

English Version

**Test method for mechanical properties of flexible opto-electric
circuit boards under thermal stress
(IEC 63251:2023)**

Méthode d'essai des propriétés mécaniques des circuits
optoélectriques souples sous contrainte thermique
(IEC 63251:2023)

Prüfverfahren für mechanische Eigenschaften von
elektrisch-optischen Leiterplatten unter
Wärmebeanspruchung
(IEC 63251:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 63251:2023 (E)

European foreword

The text of document 91/1898/FDIS, future edition 1 of IEC 63251, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63251:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2024-09-06
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2026-12-06

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Endorsement notice

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60793-2 (series) NOTE Approved as EN 60793-2 (series)

IEC 62496-3-1 NOTE Approved as EN 62496-3-1 [63251:2024](#)

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Annex ZA (normative)

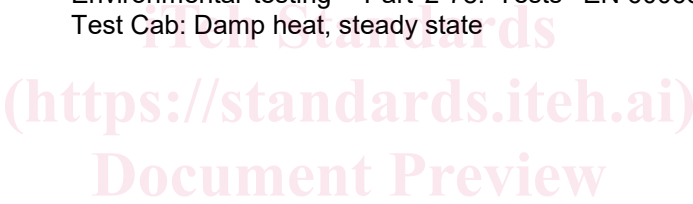
Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests Test B: Dry heat	-EN 60068-2-2	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests Test N: Change of temperature	-EN IEC 60068-2-14	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests Test Cab: Damp heat, steady state	-EN 60068-2-78	-



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IEC 63251

Edition 1.0 2023-11

INTERNATIONAL STANDARD

NORME INTERNATIONALE



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INTERNATIONAL
ELECTROTECHNICAL
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COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.180

ISBN 978-2-8322-7750-8

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHOD FOR MECHANICAL PROPERTIES OF FLEXIBLE OPTO-ELECTRIC CIRCUIT BOARDS UNDER THERMAL STRESS

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IEC 63251 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1898/FDIS	91/1914/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.